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United States Patent [19]

Feng

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[45] **Date of Patent: ** Dec. 8, 1992**

[54] **INTEGRATED CIRCUIT EXTRACTION TOOL**

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[**] Term: **14 Years**

[21] Appl. No.: **589,479**

[22] Filed: **Sep. 27, 1990**

[52] **U.S. Cl.** **D8/52**

[58] **Field of Search** D8/14, 51, 52; 81/3.8; 29/758, 764, 747; 294/99.2, 33; D28/55

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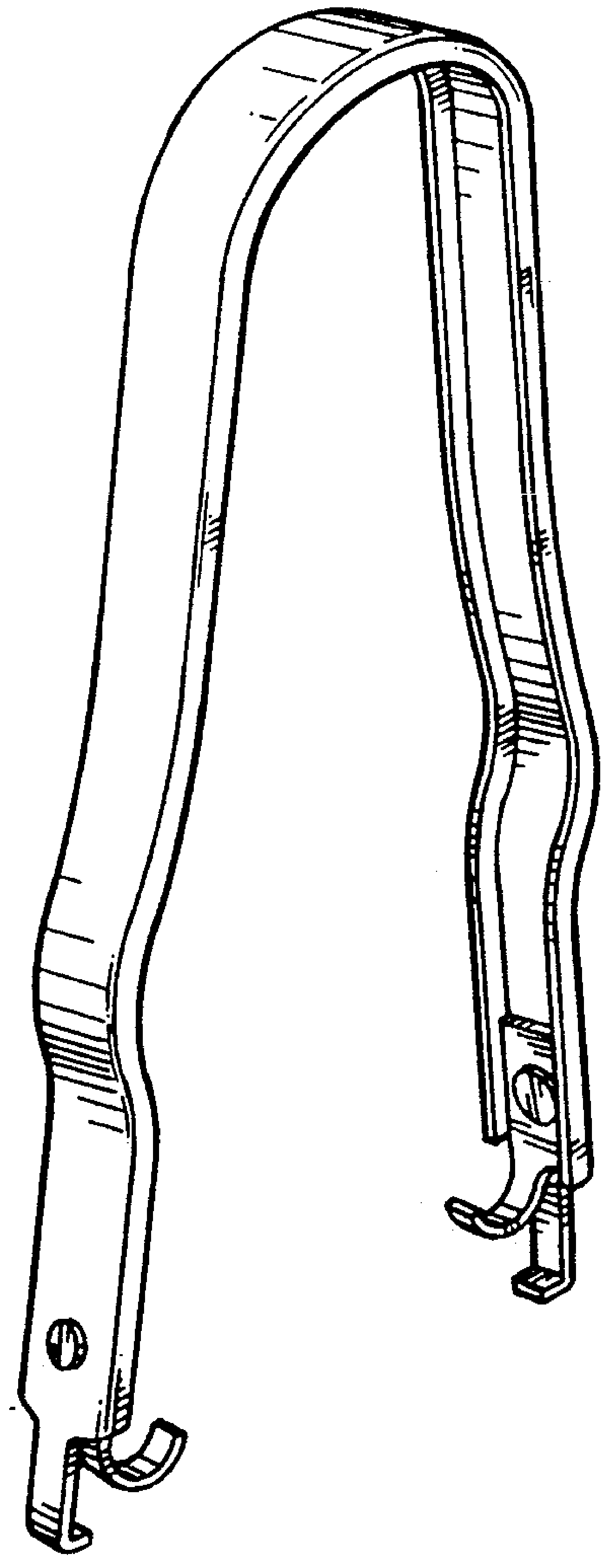
[57] **CLAIM**

The ornamental design for an integrated circuit extraction tool, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a Integrated Circuit Extraction Tool showing my new design;
FIG. **2** is a front elevational view thereof;
FIG. **3** is a rear elevational view thereof;
FIG. **4** is a left side elevational view thereof;
FIG. **5** is a right side elevational view thereof;
FIG. **6** is a top plan view thereof; and,
FIG. **7** is a bottom plan view thereof.



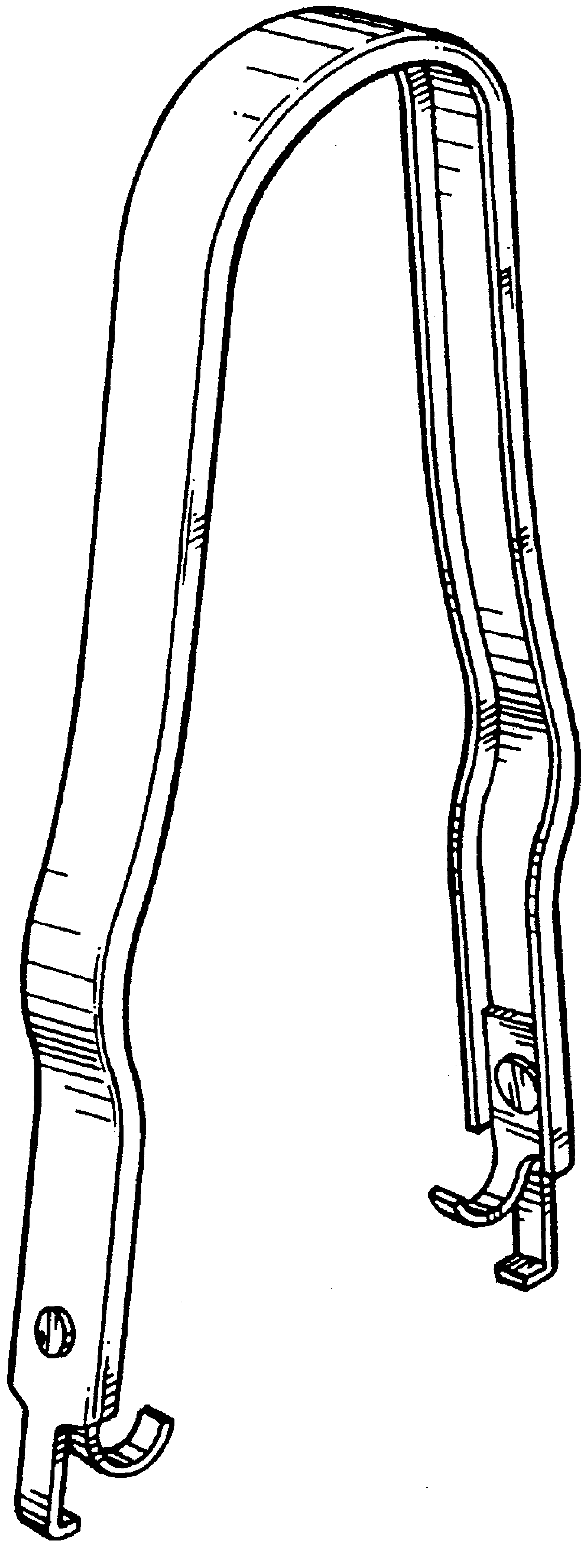


FIG. 1

FIG. 6

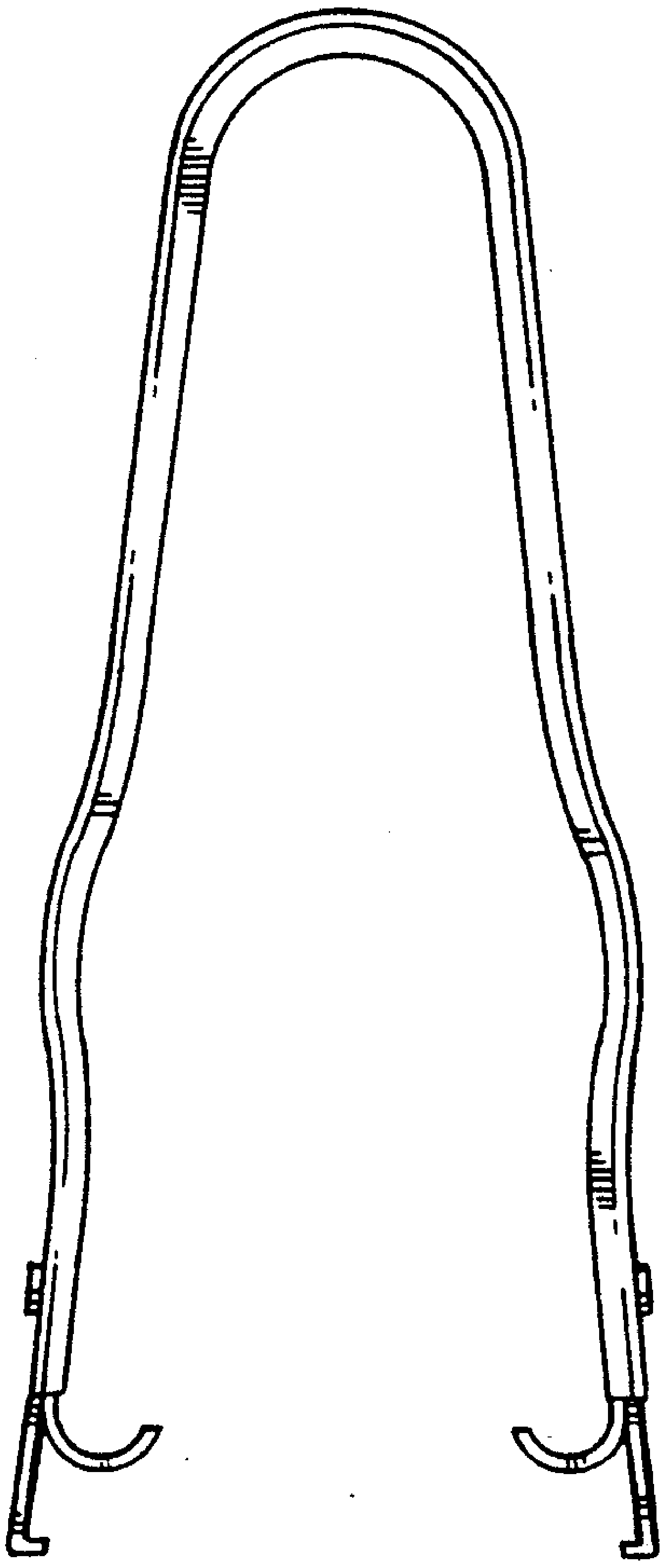


FIG. 2

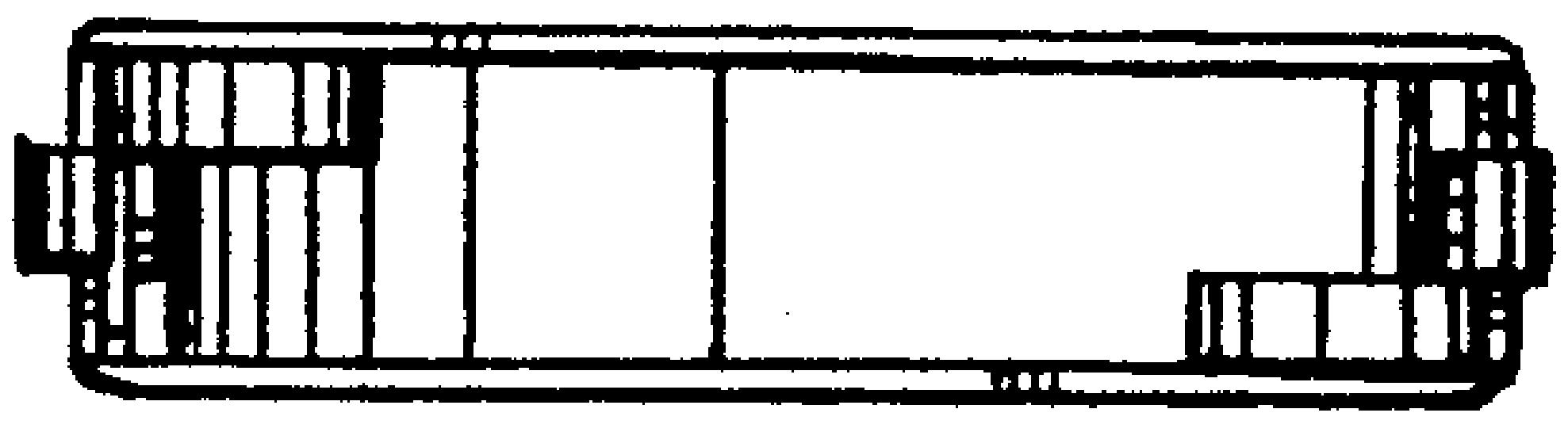


FIG. 7

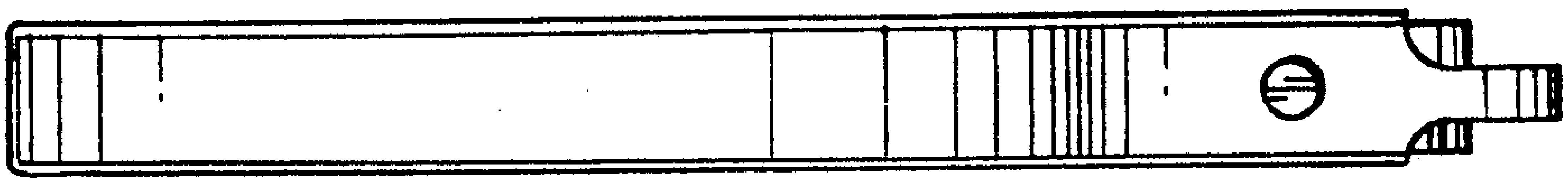


FIG. 4

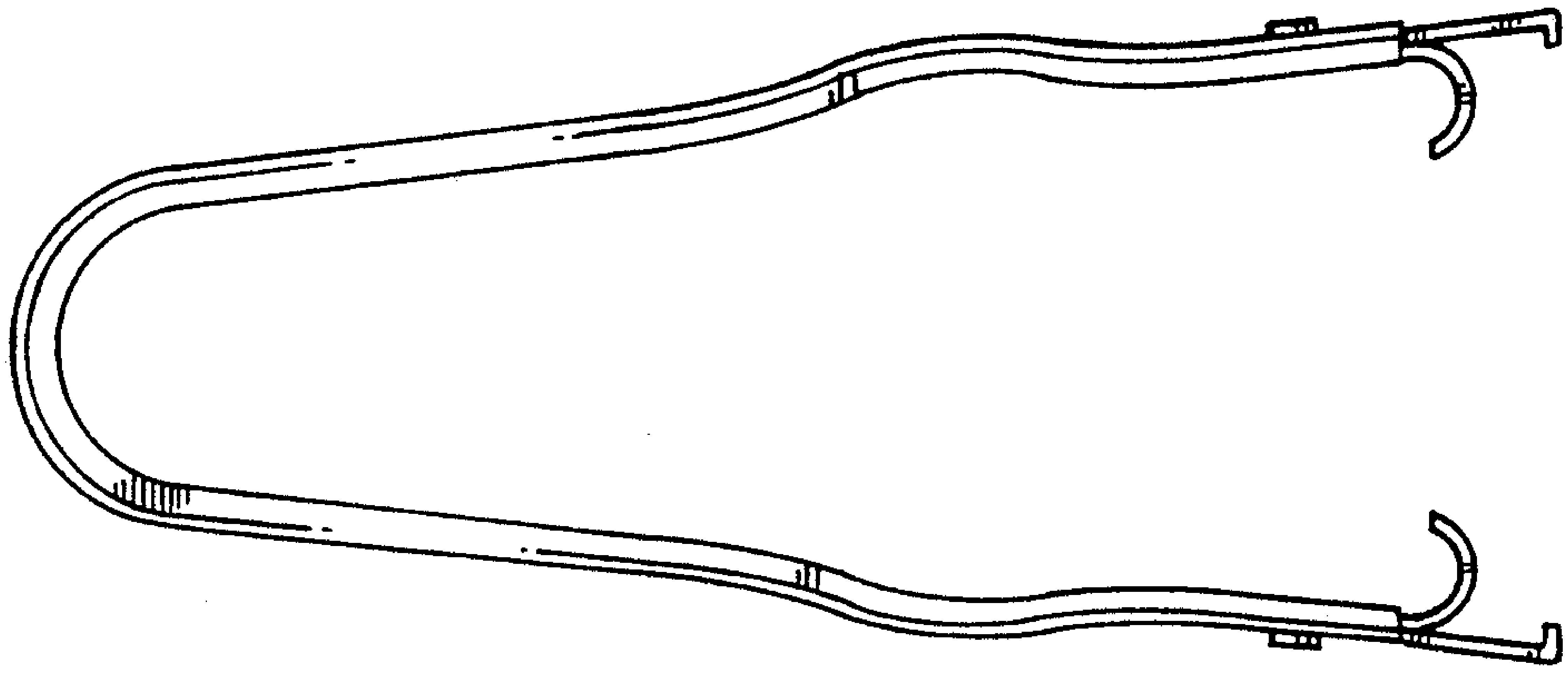


FIG. 3

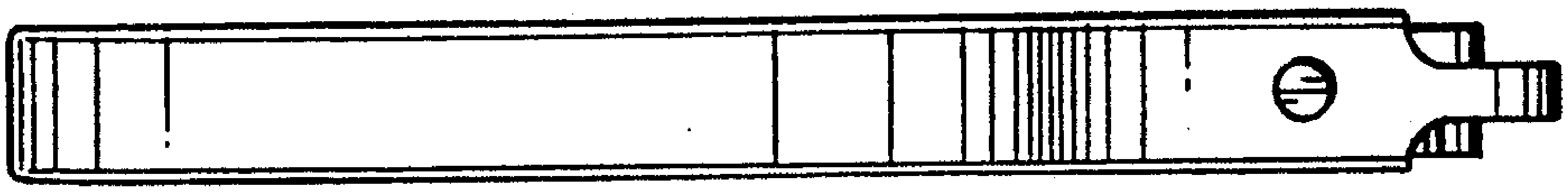


FIG. 5